

1/13

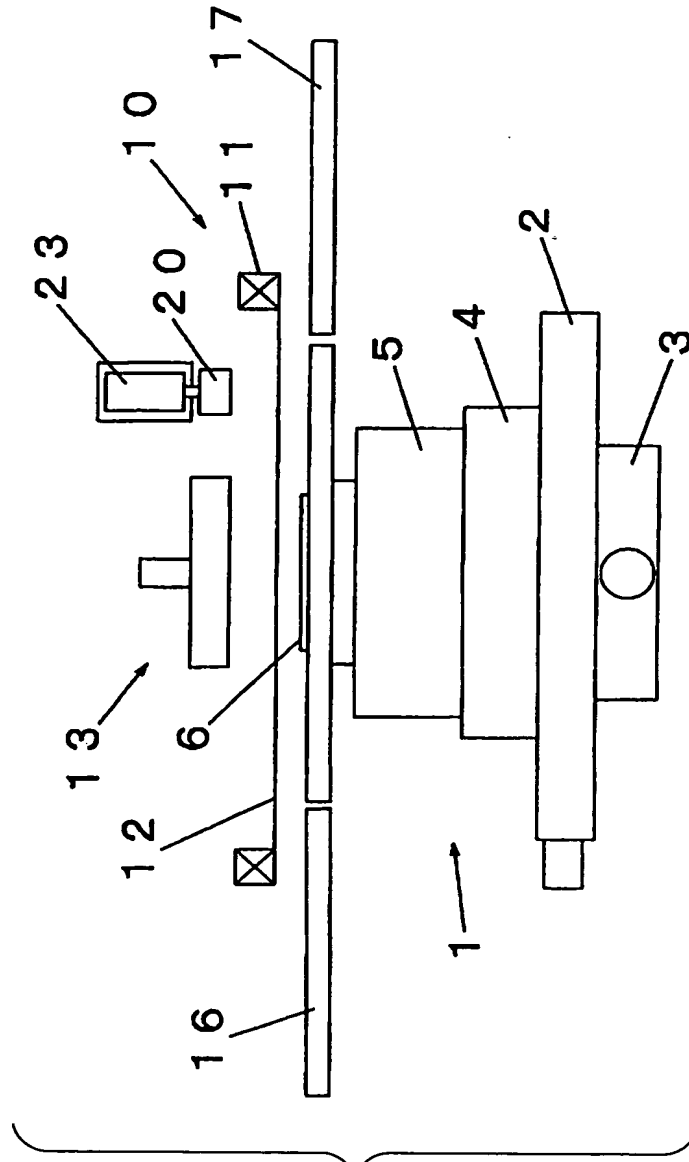


FIG. 1

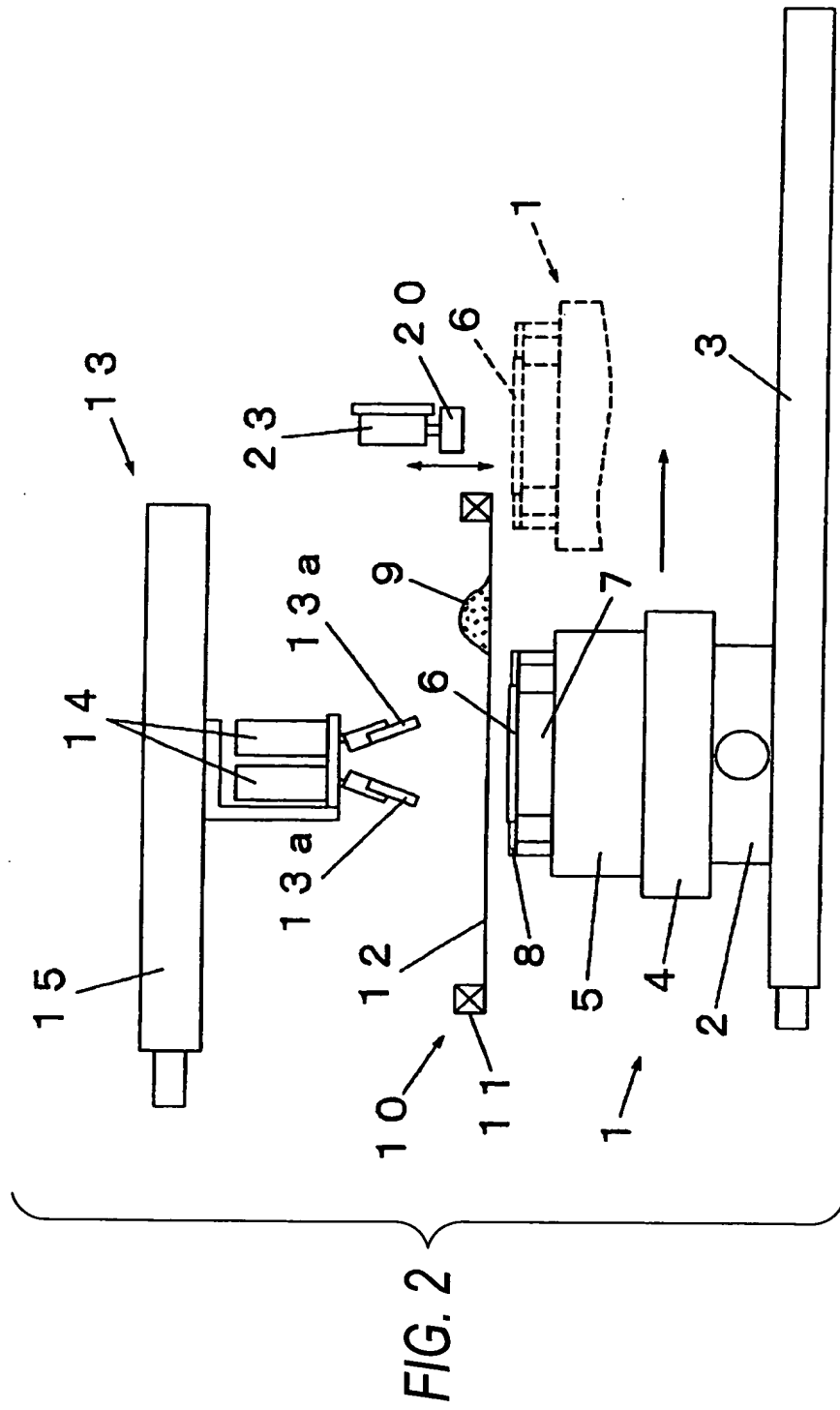


FIG. 3

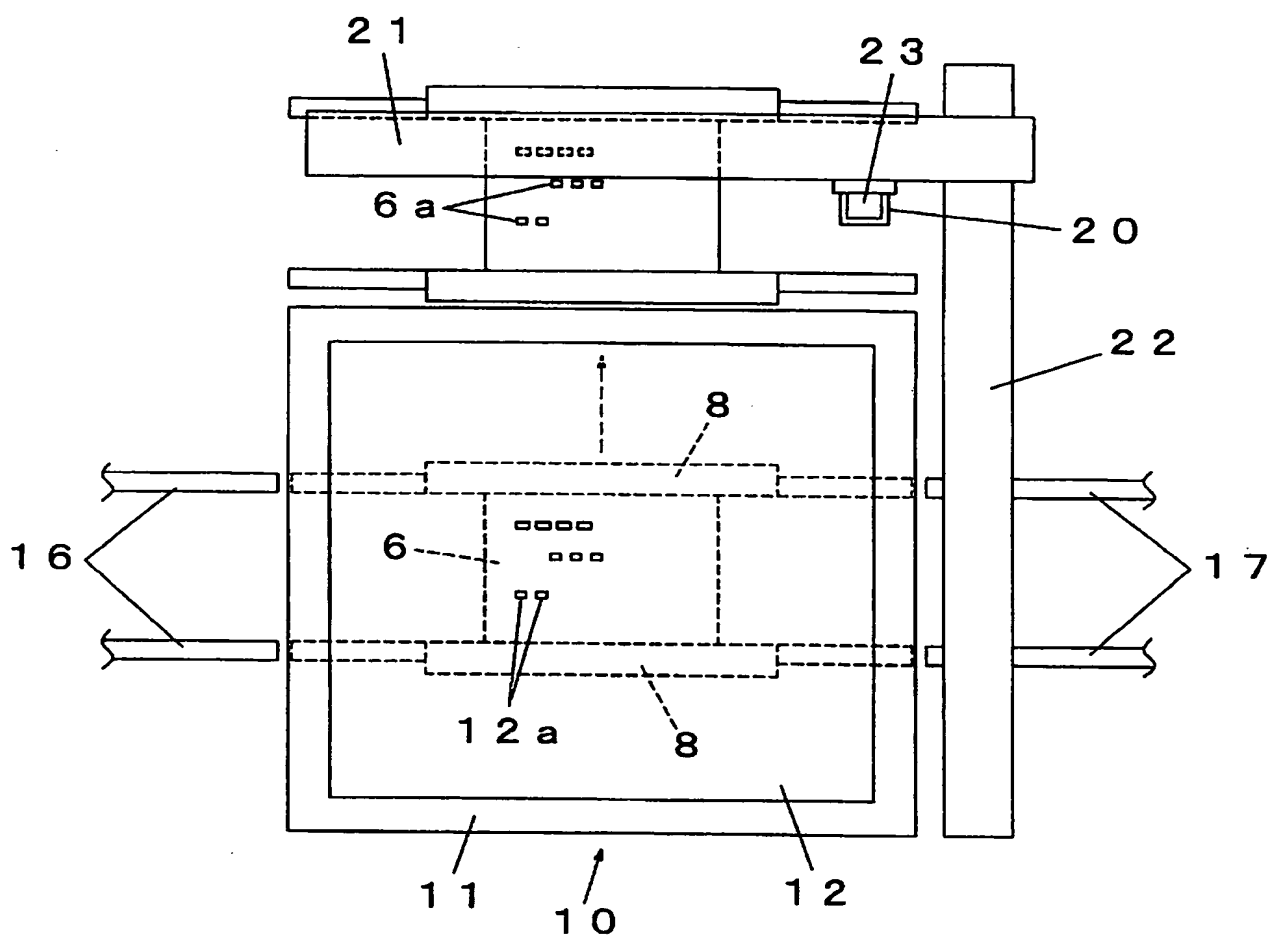


FIG. 4

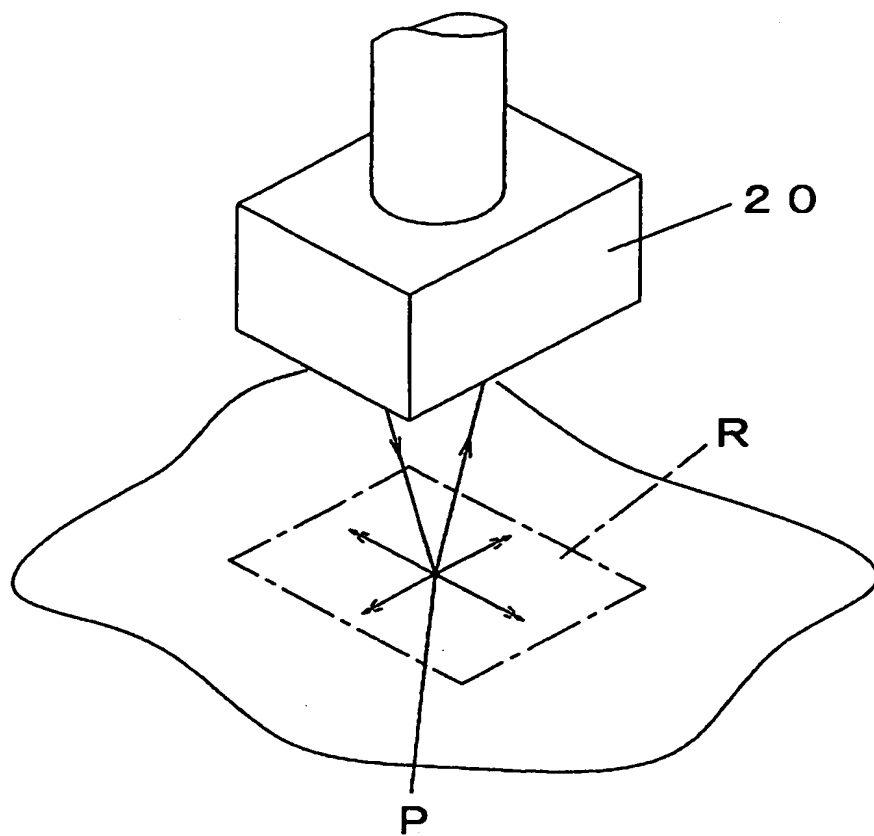
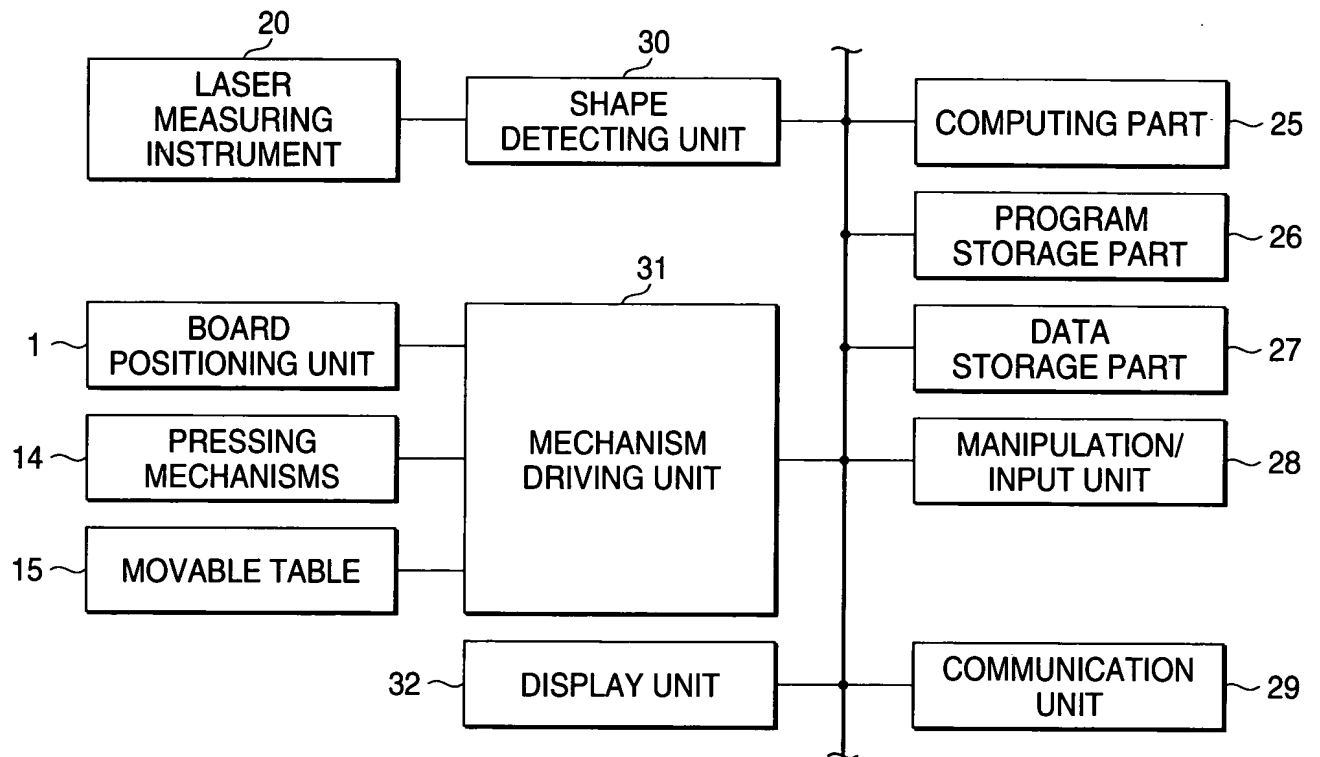
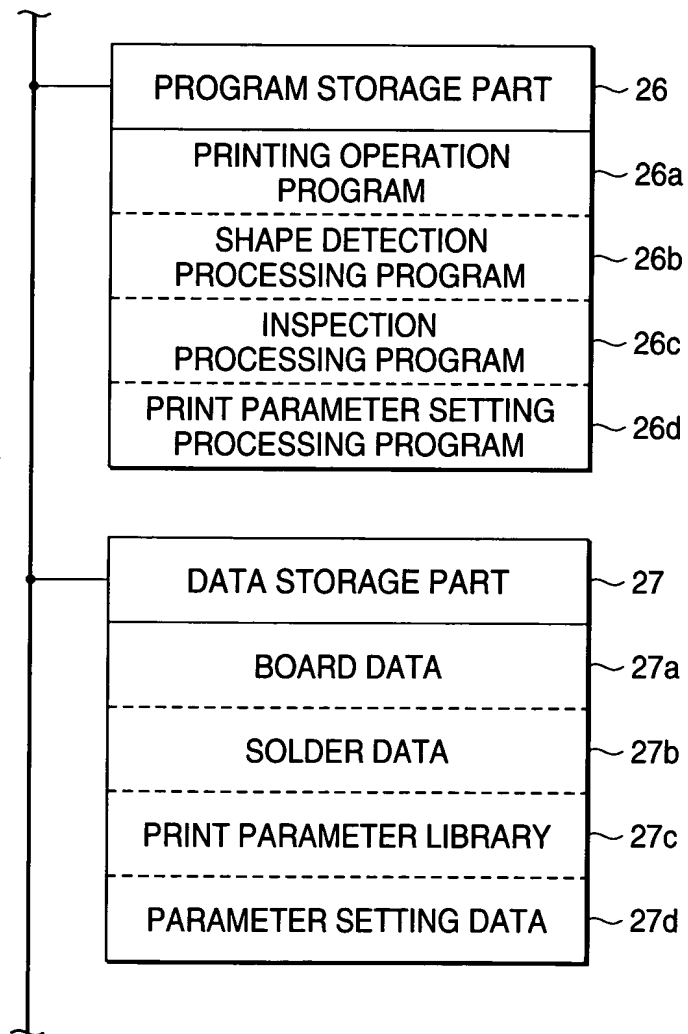


FIG. 5



*FIG. 6*

*FIG. 7*

PATTERN NAME	A	B	C	
PARAMETER \ SOLDER TYPE	S1	S2	S3	
SQUEEGEE MOVEMENT SPEED	V1	V2	V3	
PRINTING PRESSURE	P1	P2	P3	
PLATE RELEASE PATTERN	I	II	III	
PLATE RELEASE SPEED	v1	v2	v3	

FIG. 8

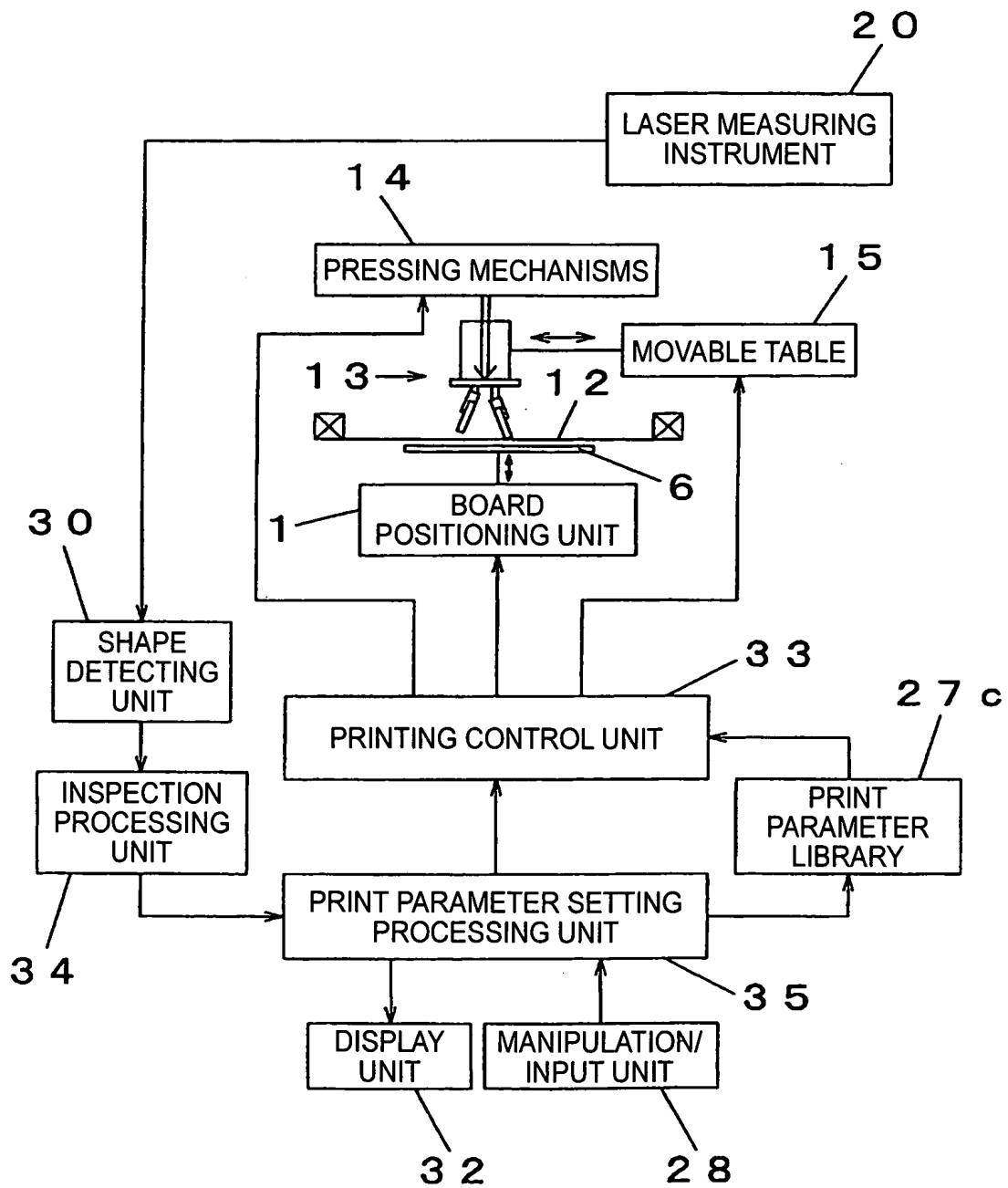




FIG. 9

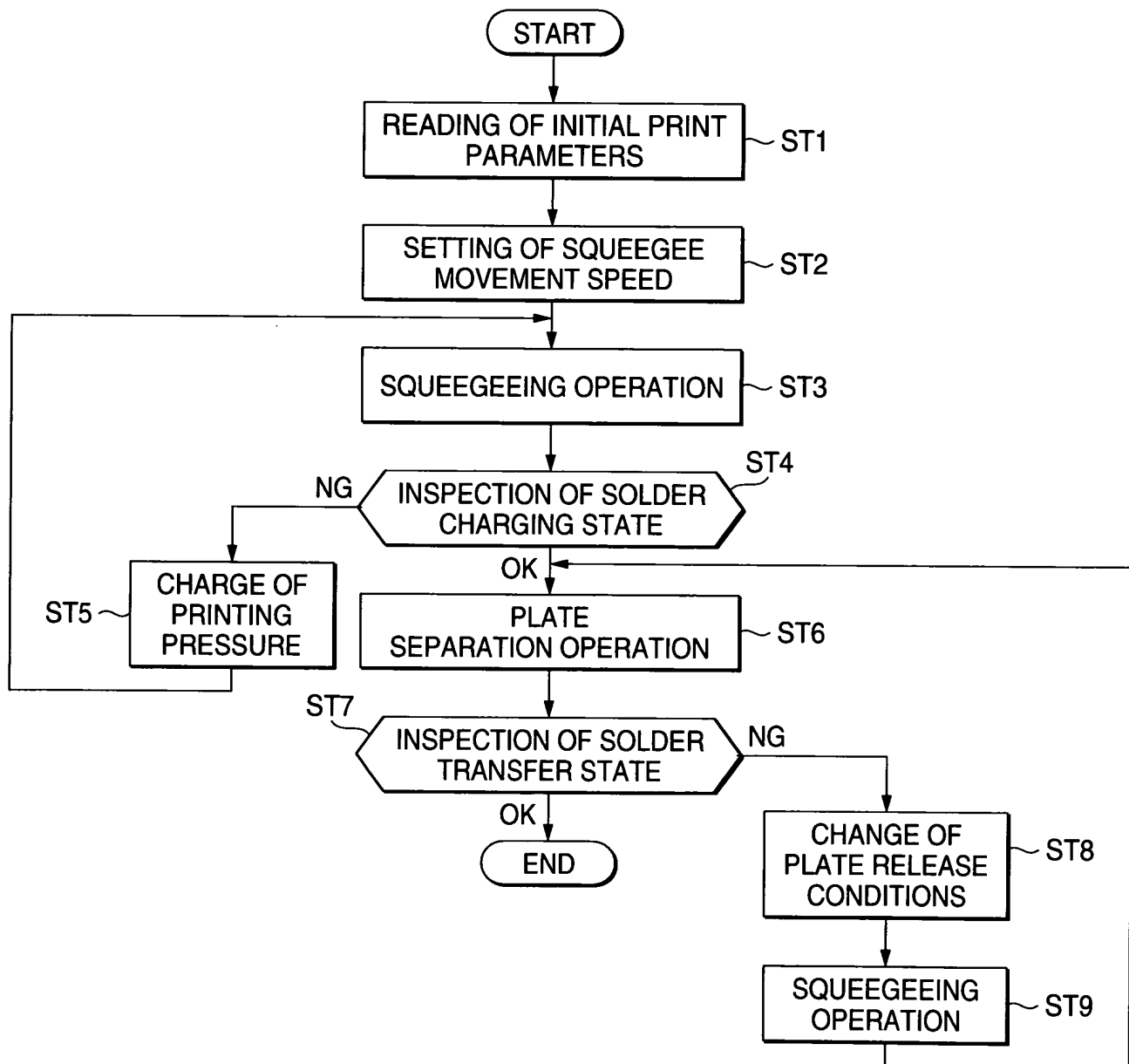


FIG. 10 (a)

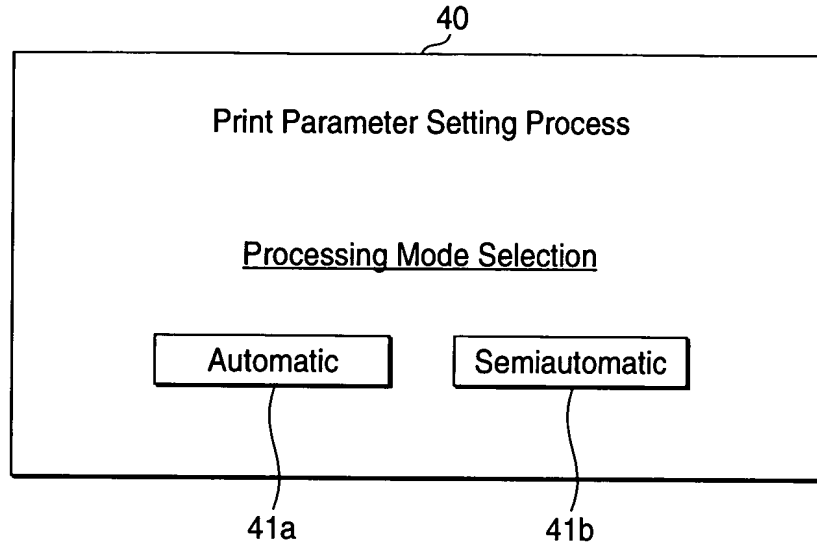
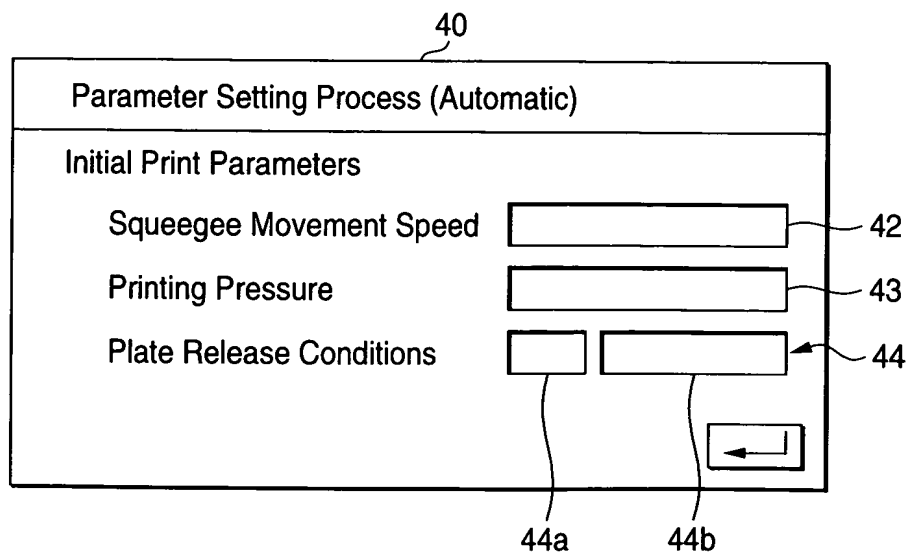


FIG. 10 (b)



**FIG. 11 (a)**

40

Parameter Setting Process (Automatic)

Parameter Confirmation

Squeegee Movement Speed

42

Printing Pressure

43

Plate Release Conditions

44

OK

45a

Re-Setting

45b

**FIG. 11 (b)**

40

Parameter Setting Process (Automatic)

Parameter Name

46

Solder Type

47

Registration

48

FIG. 12

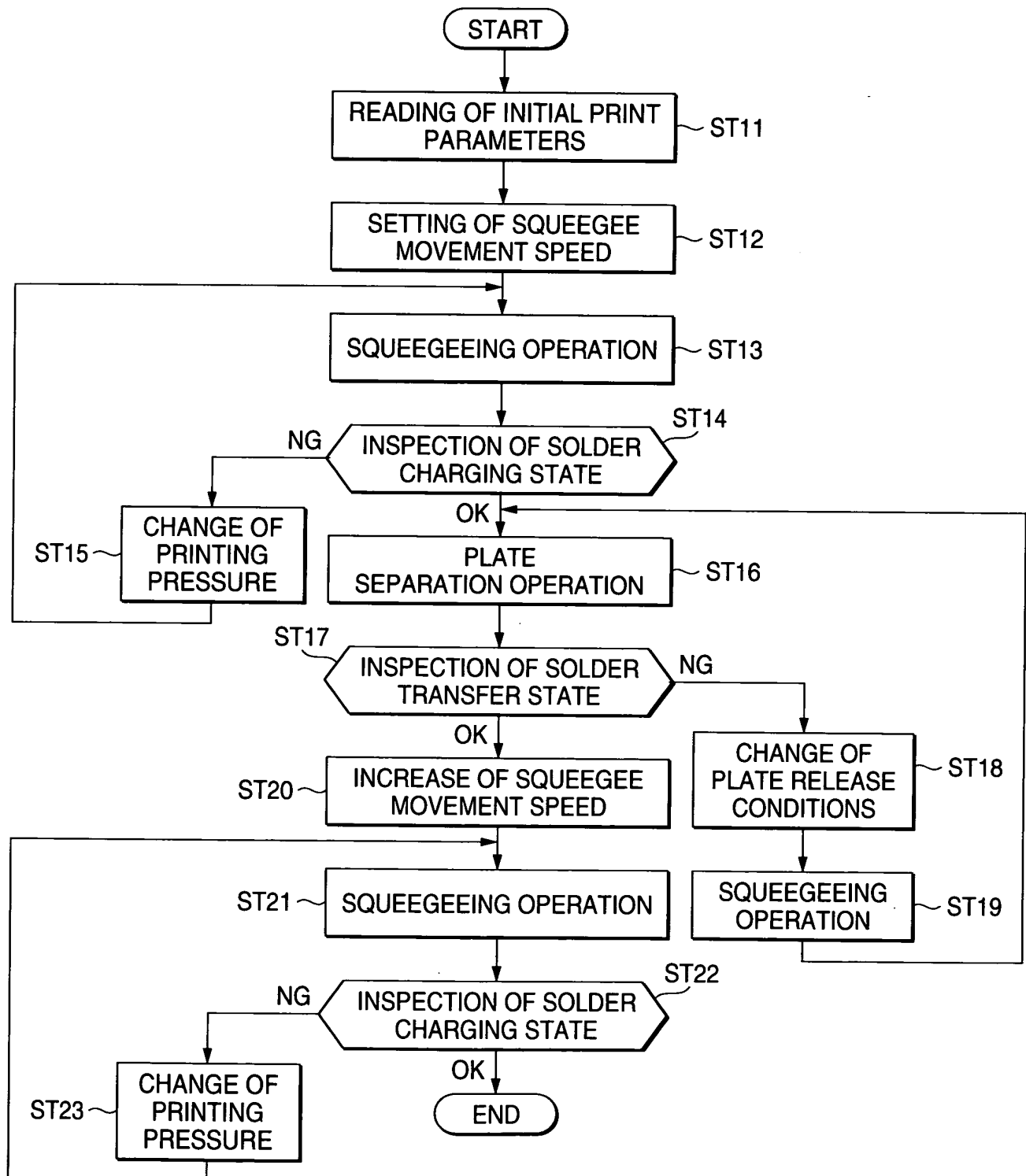


FIG. 13 (a)

40

Parameter Setting Process (Semiautomatic)

Step 1

Squeegee Movement Speed  49

FIG. 13 (b)

40

Parameter Setting Process (Semiautomatic)

Squeegee Movement Speed  50

Step 2

Printing Pressure  51

FIG. 13 (c)

40

Parameter Setting Process (Semiautomatic)

Squeegee Movement Speed  50

Printing Pressure  52

Step 3

Plate Release Conditions  53a  53b 53